


# MATERIAL DECLARATION SHEET

**BOURNS®**

Material Number	CRN2512 Series			
Product Line	Fixed Resistors			
Compliance Date	08/05/2025			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic	Substrate	34.743	Aluminum oxide	1344-28-1	96	79.933	83.263
				Silicon dioxide	14808-60-7	2	1.665	
				Magnesium oxide	1309-48-4	2	1.665	
2	Top conductor	Copper	0.287	Copper	7440-50-8	85	0.585	0.688
				None-lead Glass	65997-18-4	15	0.103	
3	Bottom conductor	Copper	0.806	Copper	7440-50-8	85	1.642	1.932
				None-lead Glass	65997-18-4	15	0.29	
4	Resistance layer	Copper alloy	1.95	Copper	7440-50-8	55	2.57	4.673
				Nickel	7440-02-0	35	1.636	
				None-lead Glass	65997-18-4	10	0.467	
5	First encapsulating	Glass	0.389	None-lead Glass	65997-18-4	100	0.932	0.932

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6	Overcoat	Resin	0.845	Epoxy Resin	25036-25-3	100	2.025	2.025
7	Side conductor	NiCr	0.814	Nickel	7440-02-0	56	1.658	1.951
				Chromium	7440-47-3	44	0.293	
8	Ni Plating	Nickel	0.687	Nickel	7440-02-0	100	1.646	1.646
9	Sn Plating	Tin	1.031	Tin	7440-31-5	100	2.471	2.471
10	Marking	Resin	0.175	Polymer	29690-82-2	70	0.293	0.419
				Titanium dioxide	1317-80-2	30	0.126	
		Total weight	41.727					

**This Document was updated on: 08/05/2025**

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.
  - a. "Compliance Date" is not the date supplier submits the MDS, but when the product was first compliant with RoHS.
  - b. "This Document was updated on:" is where we indicate when supplier submits the MDS. All previous MDS must be archived for traceability in the future.
  - c. Material weights for components less than 100mg (most Semiconductor products) should be listed in milligrams. This avoids all those zeros and round off issues.